

Optical Image Stabilization (OIS) Controller & Driver

CMOS LSI

LC898121XA

Overview

The LC898121XA is a system LSI integrating a digital signal processing function for Optical Image Stabilization (OIS) and a saturation—driven H bridge driver function.

Features

Digital Signal Processing

- Built-in Digital Servo Circuit
- Built-in Gyro Filter
- AD Converter
 - ◆ 12 Bit
 - Input 3ch
 - Equipped with a Sample-hold Circuit
- DA Converter
 - ♦ 8 Bit
 - ♦ Output 2ch
- Built–in Serial I/F Circuit (4–wire SPI or 2–wire I²C–Bus Interface)
- Built-in Hall Bias Circuit
- Built-in Hall Amp
- Built-in OSC (Oscillator)
 - ◆ Typ. 48 MHz
- Built-in LDO (Low Drop-Out Regulator)
 - Generation Logic Power (Typ 1.8 V)
- Digital Gyro I/F for the Companies (Please Refer for the Details)

Motor Driver

- Saturation–drive H Bridge x2ch
- I_O max: 300 mA

Package

- WLCSP40, 2.44 mm x 3.94 mm, Thickness Max 0.65 mm
- This is a Pb-Free and Halogen Free Device

Power Supply Voltage

- DA/VGA: DAOPVDD = 2.6 V to 3.6 V
- AD: ADVDD = 2.6 V to 3.6 V
- IO/OSC/LDO: DVDD30 = 2.6 V to 3.6 V
- Driver: VM = 2.6 V to 5.5 V
- Core Logic: Use built-in LDO/External VDD: DVDD18 = 1.8 V ±10%



MARKING DIAGRAM

8182 YMX## 17A

8121 = Specific Device Code

Y = Year M = Month

X = Assembly Location

= Conversion Character Representing Assembly Lot

ORDERING INFORMATION

Device	Package	Shipping [†]
LC898121XA-MH	WLCSP40, 2.44 x 3.94 (Pb-Free /	4000 / Tape & Reel
	Halogen Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

LC898121XA

BLOCK DIAGRAM

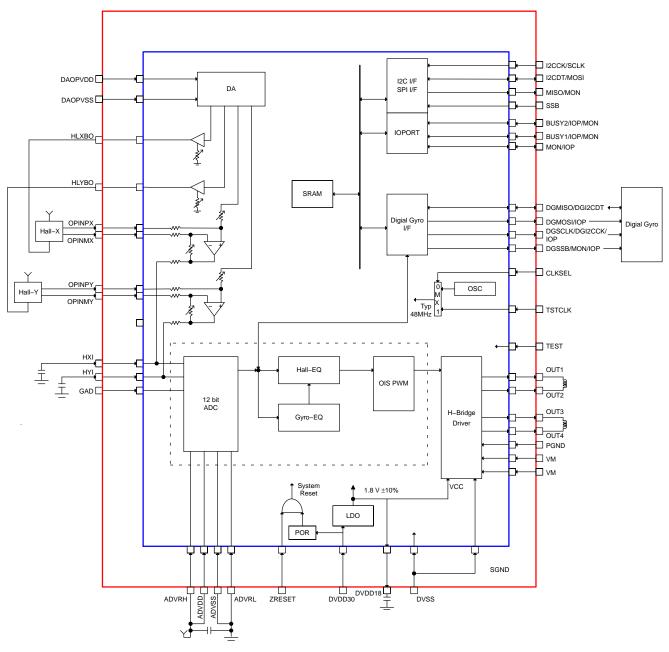


Figure 1. Example of Wiring Diagram [Hall] in LC898121XA (WLP40)

LC898121XA

PIN ASSIGNMENT

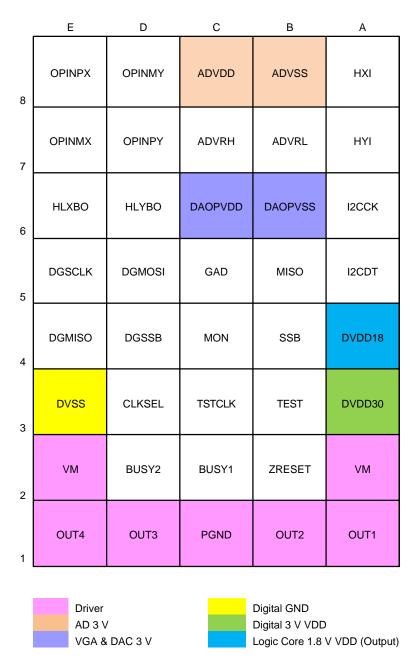


Figure 2. WLP40 Bottom View

LC898121XA

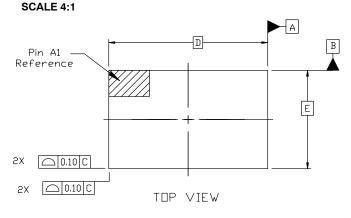
PIN DESCRIPTION (Type - I: INPUT, O: OUTPUT, B: BIDIRECTION, P: Power)

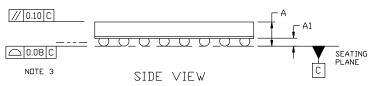
Ball No	Pin Name	Туре	Description	
A1	OUT1	0	Driver Output	
A2	VM	Р	Driver VDD (2.6 V to 5.5 V)	
A3	DVDD30	Р	Logic 3 V VDD (2.6 V to 3.6 V)	
A4	DVDD18	Р	LDO Power supply out (Logic Core VDD (typ 1.8 V))	
A5	I2CDT	В	I2C_IF data (B) / SPI IF data (I)	
A6	I2CCK	I	I2C_IF clock / SPI IF clock	
A7	HYI	I	Hall-Y AD input	
A8	HXI	I	Hall–X AD input	
B1	OUT2	0	Driver output	
B2	ZRESET	Ţ	HardWafer Reset	
B3	TEST	I	SPI & External clock case sets [1]. other cases set [0]	
B4	SSB	В	SPI I/F Chip Select (I) / General–purpose IOPORT(B) / inner signal monitor (O)	
B5	MISO	В	SPI I/F data (O) / inner signal monitor / General-purpose IOPORT	
B6	DAOPVSS	Р	DA&OpAmp VSS	
B7	ADVRL	I	ADC ReferenceVoltage Low input	
B8	ADVSS	I	AD GND	
C1	PGND	Р	Driver GND	
C2	BUSY1	В	BUSY1 (O) / General-purpose IOPORT (B) / inner signal monitor (O)	
C3	TSTCLK	Ţ	CLKSEL = 1: External Clock, CLKSEL = 0: change pin of I ² C (0) and SPI (1)	
C4	MON	В	inner signal monitor / general-purpose IOPORT	
C5	GAD	I	General AD input	
C6	DAOPVDD	Р	DA&OpAmp VDD (2.6 V to 3.6 V)	
C7	ADVRH	I	ADC ReferenceVoltage High input	
C8	ADVDD	Р	AD VDD (2.6 V to 3.6 V)	
D1	OUT3	0	Driver output	
D2	BUSY2	В	BUSY2 (O) / General-purpose IOPORT (B) / inner signal monitor (O)	
D3	CLKSEL	I	change pin of OSC (0) and External clock (1)	
D4	DGSSB	В	Digital Gyro SPI IF Chip Select (O) / inner signal monitor (O) / General-purpose IOPORT (B)	
D5	DGMOSI	В	Digital Gyro (4-wire) IF data (O) / General-purpose IOPORT (B)	
D6	HLYBO	0	Hall-Y Bias (Current drive)	
D7	OPINPY	1	Hall-Y OpAmp input+	
D8	OPINMY	1	Hall-Y OpAmp input-	
E1	OUT4	0	Driver output	
E2	VM	Р	Driver VDD (2.6 V to 5.5 V)	
E3	DVSS	Р	Logic GND	
E4	DGMISO	В	Digital Gyro SPI IF data(I) / Digital Gyro I ² C IF data (B)	
E5	DGSCLK	В	Digtal Gyro SPI IF clock (O) / Digital Gyro I ² C IF clock (O) / General purpose IOPORT (B)	
E6	HLXBO	0	Hall-Y Bias (Current drive)	
E7	OPINMX	ļ	Hall–X OpAmp input–	
E8	OPINPX	1	Hall–X OpAmp input+	

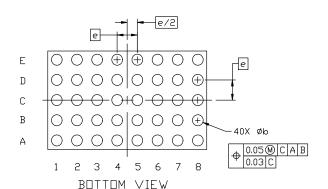




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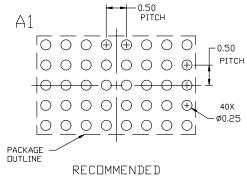




NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

	MILLIMETERS	
DIM	MIN.	MAX.
Α		0.65
A1	0.14	0.24
b	0.22	0.32
D	3.94	BSC
E	2.44	BSC
е	0.50	BSC



MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

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DESCRIPTION:	WLCSP40, 2.44X3.94		PAGE 1 OF 1	

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